Amendment After Allowance under 37 C.F.R. § 1.312

Applicant: Xiang Dai et al. Serial No.: 10/612,663 Filed: July 2, 2003 Docket No.: 200308566-1

Title: SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE HAVING A SOLDER

COLUMN ARRAY

REMARKS

This Amendment after Allowance under 37 C.F.R. § 1.312 is in response to the Notice of Allowance mailed November 20, 2007. In the Office Action, claims 8, 10, 13-14, 21, 23, 25, 28-29, and 32-35 were allowed. With this Amendment, claims 8 and 28 are amended.

Initialing of Information Disclosure Statement filed on February 8th, 2005

Applicants note that two pages of Form PTO/SB/08A of Applicants' Information Disclosure Statement (IDS) filed on February 8, 2005 were apparently received at the Patent Office (a copy of which as received by the Patent Office on February 11, 2005 is enclosed). However, none of these pages were returned to Applicants with the Examiner's initials and also are not provided on the Patent Application Information Retrieval (PAIR) system. Accordingly, Applicants respectfully request that an initialed copy of these two pages of the February 8th IDS be provided to Applicants, thereby confirming the Examiner's consideration of these references cited in the timely filed IDS.

Examiner's Amendment

Applicants appreciate the Notice of Allowance and the Examiner's Amendment. However, Applicants are amending the language added via the Examiner's Amendment in order to make claims 8 and 28 correspond more closely to the allowable subject matter of former claims 31 and 30, respectively, and to maintain antecedent basis with the preceding portions of claims 8 and 28, respectively.

In particular, both claims 8 and 28 use the terminology of "the solder column array." Accordingly, the present amendment replaces "a solder connection" (added via the Examiner's Amendment) with "the solder column array." In addition, claim 8 uses the terminology of "the wings." Accordingly, the present Amendment replaces "the wing portions" (added via the Examiner's Amendment) with "the wings." Finally, the Examiner's Amendment inadvertently omitted the term "a height" (which was present in former claims 30 and 31). Accordingly, both claims 8 and 28 have been amended to add the term "a height"

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prior to "the wings" or "the wing portions" to make claims 8 and 28 more closely conform to former claims 31 and 30, respectively.

CONCLUSION

Applicants respectfully request entry of the present Amendment and that the initialed copies of the above-referenced IDS Forms be provided to Applicants.

The Examiner is invited to contact the Applicants' representative at the below-listed telephone number to facilitate prosecution of this application.

Any inquiry regarding this Amendment and Response should be directed to either David A. Plettner at Telephone No. (408) 447-3013, Facsimile No. (408) 447-0854 or Paul S. Grunzweig at Telephone No. (612) 767-2504, Facsimile No. (612) 573-2000. In addition, all correspondence should continue to be directed to the following address:

IP Administration Legal Department, M/S 35 HEWLETT-PACKARD COMPANY P.O. Box 272400 Fort Collins, Colorado 80527-2400

Respectfully submitted,

Xiang Dai et al.

By their attorneys,

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Date: February 8, 2008 /Paul S. Grunzweig/

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